

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	9	("20020145203" "6100594" "6157080" "6172422" "6200888" "6218630" "6351028" "6407456" "6507115").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 14:33
L2	227387	(semiconductor or die or chip or IC) and (step) with (board or PCT or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 14:39
L3	209250	(semiconductor or die or chip or IC) and (step) with (board or PCT or substrate or module or carrier or hous\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 14:39
L4	218285	(semiconductor or die or chip or IC) and (step\$4 or stair\$4) with (board or PCT or substrate or module or carrier or hous\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 14:40
L5	22113	(semiconductor or die or chip or IC) and (step\$4 or stair\$4) near (board or PCT or substrate or module or carrier or hous\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 14:41
L6	8995	(semiconductor or die or chip or IC) and (step\$4 or stair\$4) near (board or PCT or substrate or module or carrier or hous\$3) and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 14:41
L7	4219	(semiconductor or die or chip or IC) and (step\$4 or stair\$4) near (board or PCT or substrate or module or carrier or hous\$3) and wir\$3 and (seal\$3 or encapsulat\$3 or mold\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 14:42
L8	2312	(semiconductor or die or chip or IC) and (step\$4 or stair\$4) near (board or PCT or substrate or module or carrier or hous\$3) and wir\$3 and (seal\$3 or encapsulat\$3 or mold\$3)	USPAT	OR	ON	2005/11/25 17:23
L9	5	("4795670" "5481436" "5510758" "6021050" "6362525").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 14:51

L10	29	("3614832" "3871015" "4283839" "4695870" "4714516" "4716049" "4866508" "4902606" "4924353" "5055907" "5148265" "5148266" "5258330" "5282312" "5346861" "5347159" "5367764" "5390844" "5398863" "5414298" "5436197" "5601678" "5656547" "5719749" "5766825" "5807766" "5853622" "5895230").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 16:07
L11	11	("6294407").URPN.	USPAT	OR	OFF	2005/11/25 16:09
L12	12	("4143456" "5136366" "5336931" "5438477" "5557150" "5629566" "5657207" "5672912" "5703405" "5786988" "5834335" "5846874").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 16:18
L13	7	("6214643").URPN.	USPAT	OR	OFF	2005/11/25 16:19
L14	1	("4567643").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 16:57
L15	62	("5311401").URPN.	USPAT	OR	OFF	2005/11/25 16:58
L16	13	("4843188").URPN.	USPAT	OR	OFF	2005/11/25 17:17
L17	1	"20020015292"	US-PGPUB; USPAT	OR	ON	2005/11/25 17:26
L18	1917	174/52.2	US-PGPUB; USPAT	OR	ON	2005/11/25 17:26
L19	4	("5832600" "6119335" "6664138" "6720209").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 17:32
L20	2	("5832600" "6222272").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 17:33
L21	2	("5989935" "6405431").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 17:34
L22	5	("6001671" "6215179" "6528893" "6566168" "6586677").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 17:49
L23	91	chris with chu	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 17:49

L24	10	("5012323" "5347159" "5347428" "5422435" "5495398" "5767570" "5903049" "5905639" "5976911" "6133637").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 17:50
L25	11	("5216278" "5296738" "5468999" "5490324" "5612576" "5721450" "5729050" "5767446" "5773895" "5893724" "5917234").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/25 18:30
L26	3669	257/678	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/25 19:09
L27	3374	257/787	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/25 19:09
S1	3408	257/774	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/02 18:46
S2	4073	257/778	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/02 18:58
S3	2615	257/786	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/02 19:06
S5	1	"20020171153"	US-PGPUB; USPAT	OR	OFF	2004/09/02 11:21
S6	1	"20020171153" and board with (insulat\$3 or dielectric)	US-PGPUB; USPAT	OR	ON	2004/09/02 11:57
S7	1	"5736791".pn.	US-PGPUB; USPAT	OR	ON	2004/09/02 18:28
S8	0	"20020171153"	USPAT	OR	OFF	2005/01/28 16:23
S9	1	"20020171153"	US-PGPUB; USPAT	OR	OFF	2005/01/28 16:24
S10	1	"20030122259"	US-PGPUB; USPAT	OR	OFF	2005/01/28 16:24

S11	2613	257/698	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 16:37
S12	3668	257/774	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 16:46
S13	3729	257/773	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 17:06
S14	4416	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 17:48
S15	2790	257/786	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 18:06
S16	1133	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 18:54
S17	2183	257/780	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:09
S18	2824	257/784	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:28

S19	16	"6482730".pn. or "6344696".pn. or "6245598".pn. or "6177725".pn. or "6153448".pn. or "6028354".pn. or "5990545".pn. or "5866949".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:32
S20	382070	(semiconductor or die or chip or IC) and (step or groove or recess or open\$3) with (board or PCT or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/25 14:38
S21	382018	(semiconductor or die or chip or IC) and (step or groove or recess or open\$3) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:39
S22	50028	S21 and (encapsulat\$3 or module)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:36
S23	129330	S21 and (encapsulat\$3 or mod\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:38
S24	55365	S23 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:38
S25	38727	S21 and (encapsulat\$3 or mod\$3) with (step or groove or recess or open\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:39
S26	17822	S25 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:40

S27	179232	(semiconductor or die or chip or IC) and (step or groove) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:39
S28	22292	S27 and (encapsulat\$3 or mod\$3) with (step or groove)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:39
S29	10051	S28 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:40
S30	2130	S29 and (step or groove) with (edge or peripher\$3 or perimeter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:42
S31	995	S29 and (step or groove) with (edge or peripher\$3 or perimeter) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:45
S32	26364	(semiconductor or die or chip or IC) and (step or groove) with (edge or peripher\$3 or perimeter) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:39
S33	5366	S32 and (encapsulat\$3 or mold\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:48
S34	2641	S33 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:48
S35	1423	S33 and wir\$3	USPAT	OR	ON	2005/01/28 19:53
S36	1109	S35 not S31	USPAT	OR	ON	2005/01/28 19:53

S37	2	"0050419".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:09
S38	1	"5345106".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:09
S39	1	"5661092".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10
S40	1	"5808359".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10
S41	1	"6166446".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10
S42	1	"6249433".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10
S43	1	"6323549".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:11
S44	1	"6436550".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:11
S45	1	"6552417".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:11
S46	15012	(semiconductor or die or chip or IC) and (step\$3 or ledge) with (edge or peripher\$3 or perimeter) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:41
S47	7660	(semiconductor or die or chip or IC) and (step\$3 or ledge) with (edge or peripher\$3 or perimeter) with (board or PCB or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:42
S48	3226	(semiconductor or die or chip or IC) and (step\$3 or ledge) with (edge or peripher\$3 or perimeter) with (board or PCB or module or carrier or mount\$3)	USPAT	OR	ON	2005/01/28 20:43
S49	2703	S48 not S35	USPAT	OR	ON	2005/01/28 20:43
S50	98	S48 not S35 and (wire) and (encapsulat\$3 or mold\$3)	USPAT	OR	ON	2005/01/28 20:47
S51	58	S48 not S35 and (wiring) and (encapsulat\$3 or mold\$3)	USPAT	OR	ON	2005/01/28 20:47
S52	58	S49 and (wiring) and (encapsulat\$3 or mold\$3)	USPAT	OR	ON	2005/01/28 20:49
S53	2	S47 and (wiring) and (encapsulat\$3 or mold\$3)	JPO	OR	ON	2005/01/28 20:58

S54	2	"5964174"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:58
S55	14	"5864174"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 21:14
S56	1	"4695870".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:00
S57	1	"4855869".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:00
S58	1	"5030796".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:00
S59	1	"5175610".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:01
S60	1	"5216278".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:01
S61	1	"5264726".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:05
S62	1	"5291374".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:05
S63	1	"5311057".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
S64	1	"5319241".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
S65	1	"5436203".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
S66	1	"5450283".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
S67	1	"5455456".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
S68	1	"5467253".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
S69	1	"5477611".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
S70	1	"5496775".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
S71	1	"5508556".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
S72	1	"5528083".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07

S73	1	"5621242".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
S74	1	"5621242".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
S75	1	"5633785".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
S76	1	"5686362".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
S77	1	"5789809".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
S78	1	"5866949".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
S79	3835	257/678	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 21:34
S80	2	"5216278".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 21:34
S81	14	"5864174"	USPAT	OR	OFF	2005/07/12 16:32
S82	113410	(semiconductor or die or dice or chip or IC) and (step or stair) with (substrate or module or carrier or hous\$3 or board or tape)	USPAT	OR	ON	2005/07/12 16:35
S83	46679	(semiconductor or die or dice or chip or IC) same (step or stair) with (substrate or module or carrier or hous\$3 or board or tape)	USPAT	OR	ON	2005/07/12 16:35
S84	7032	(semiconductor or die or dice or chip or IC) same (step or stair) with (substrate or module or carrier or hous\$3 or board or tape) with (conductive or wiring)	USPAT	OR	ON	2005/07/12 16:35
S85	1171	(semiconductor or die or dice or chip or IC) same (step or stair) with (substrate or module or carrier or hous\$3 or board or tape) with (conductive or wiring) and wire near bonding	USPAT	OR	ON	2005/07/12 19:08
S86	1	"4707724".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:53
S87	1	"4835120".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:54

S88	1	"4906802".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:54
S89	1	"5065281".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:54
S90	1	"5083189".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:54
S91	1	"5136471".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:55
S92	1	"5083189".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:55
S93	1	"5157588".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:55
S94	1	"5225499".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:55
S95	1	"5249101".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:56
S96	1	"5252783".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:56
S97	1	"6841857"	USPAT	OR	ON	2005/07/12 19:11
S98	2	"0050419".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:08
S99	1	"5345106".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:08
S10 0	1	"5661092".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:08
S10 1	1	"5808359".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:09
S10 2	1	"6166446".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:09
S10 3	1	"6249433".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:09
S10 4	1	"6323549".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:10
S10 5	1	"6436550".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:10
S10 6	1	"6552417".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:10
S10 7	262	"5216278"	USPAT	OR	ON	2005/07/12 19:11
S10 8	4442	361/704	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/13 22:21